

Standardization of Electrical Specifications for Test Socket Contactors

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ISC & Prowell



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In the Beginning...

- **Transmission speed**

1.5Mbps ► 14Mbps ► 225Mbps ► 1Gbps ► 20Gbps ► 6G, 1Tbps

- **Transmission line**

Cable(Km~m) ► PCB(Cm~mm) ► Connector/Socket(1~10mm)

- **Equipment & Load BD'**

Cable-Connector-PCB(Load BD')-Connector-Cable ► m~Cm

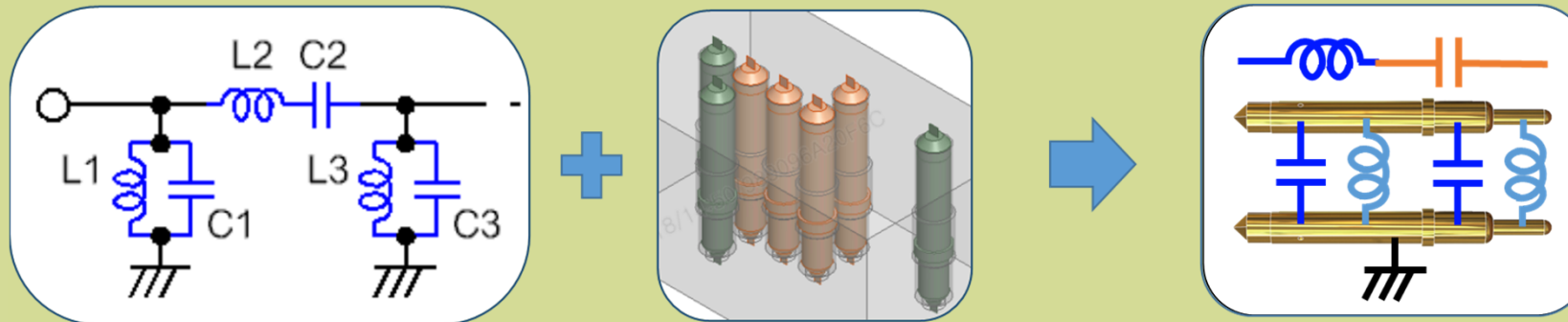
DUT-Test socket(0.1mm~10mm) - PCB Pad & Trace

- **Requirement specification**

SWR(1.5:1) ► Inductance(<1nH) ► IL (-1dB)/RL(-10dB)/XT(-40dB)

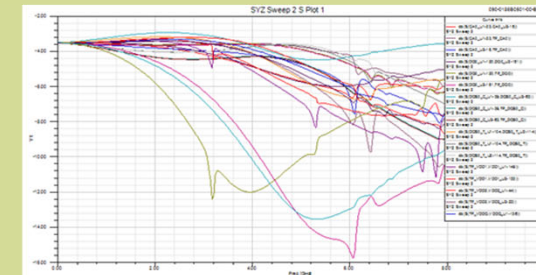
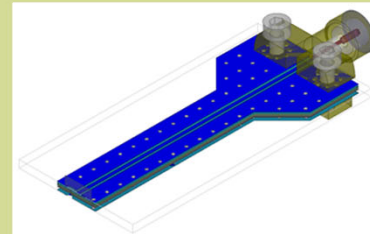
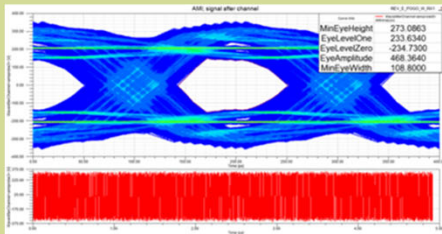
Test socket, Passive or Active Element?

- S-parameter requirements are also taken for granted in test sockets.
- **Some customers require S-parameters just for contactors.**
- However, S-Parameter cannot be analyzed using Contactor alone.
 - Must be a signal pin and at least one ground pin
 - Material of housing that makes it up also affects the S-parameter.



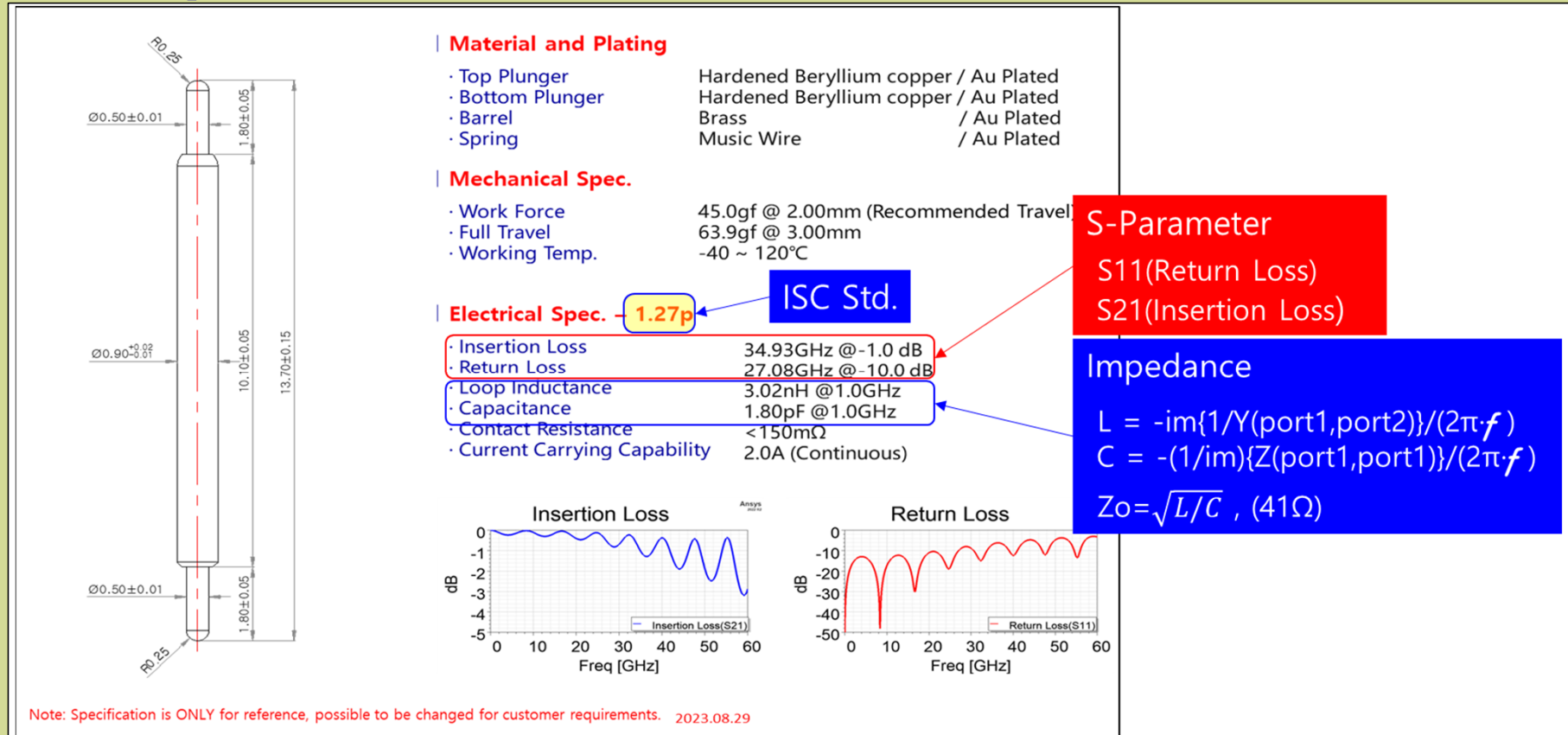
Test socket, Passive or Active Element?

- Fortunately, With the development of 3D FEA,
 - Even non-experts, to generate data without complex calculations.
- This presentation, I will explain through the 3D FEA case of POGO

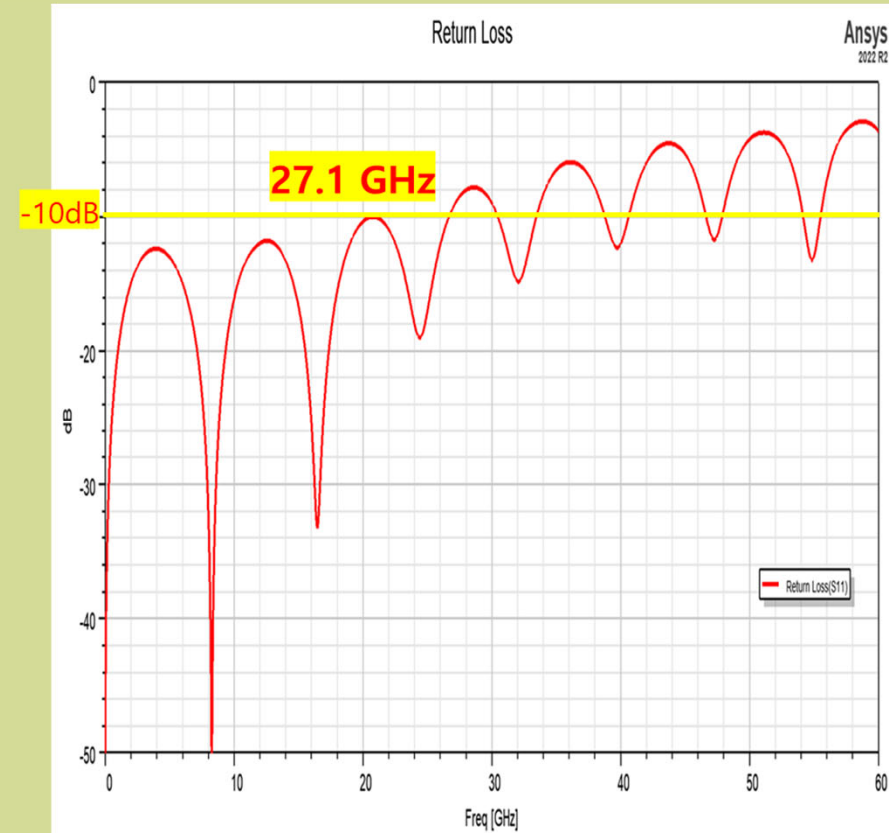
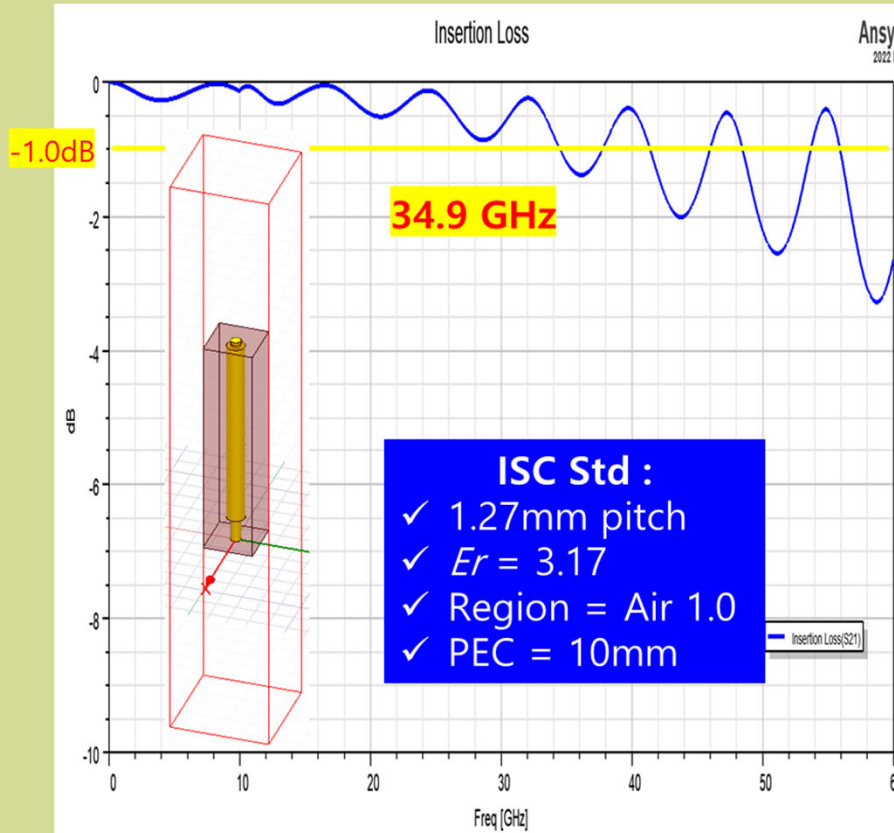


- The FEA tool used is Ansys HFSS,
: FEA detailed conditions apply ISC “RF Simulation STD Manual 2020 ver1.2”.

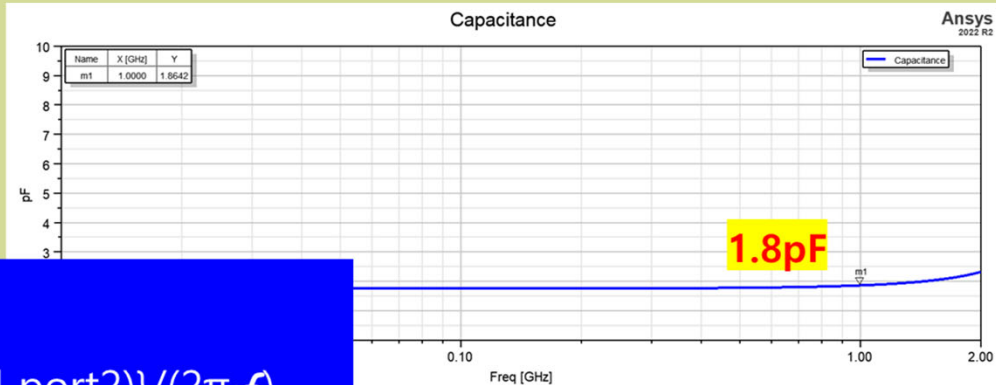
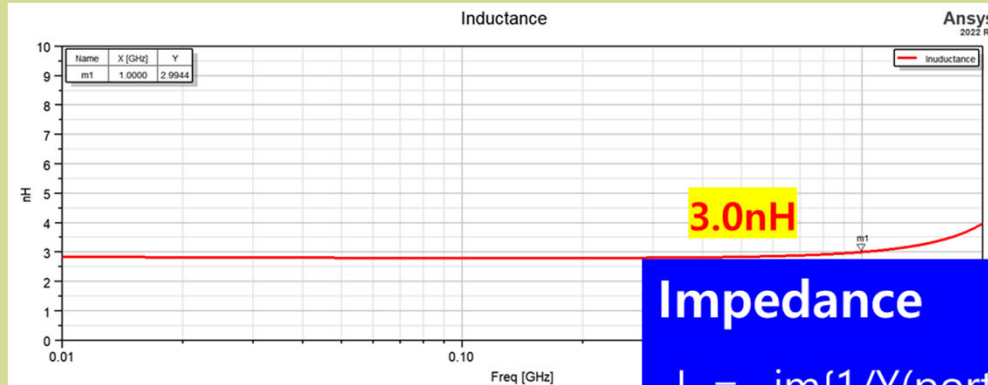
Example Data sheet



Example Data sheet



Example Data sheet

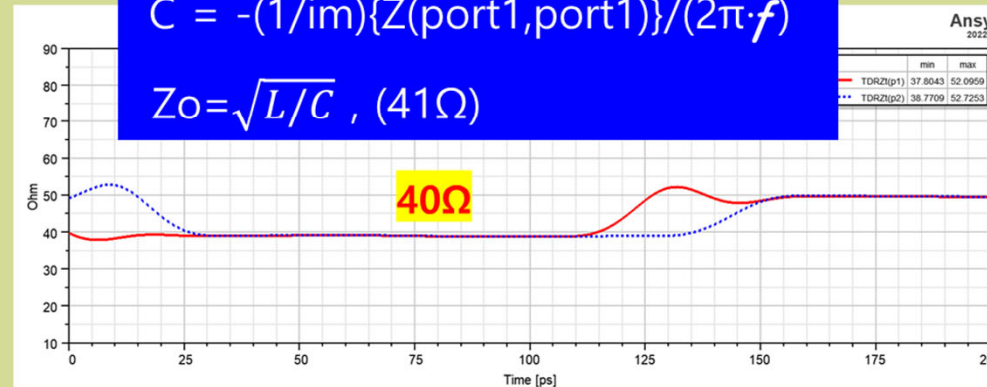


Impedance

$$L = -\text{im}\{1/Y(\text{port1}, \text{port2})\} / (2\pi \cdot f)$$

$$C = -(1/\text{im})\{Z(\text{port1}, \text{port1})\} / (2\pi \cdot f)$$

$$Z_0 = \sqrt{L/C} , (41\Omega)$$



Problem

Item		Vendor B		Remark
Dimension	OD0.9(0.5) * 13.7(1.8+10.1+1.8)mm			
Top Plunger	Hardened Beryllium copper / Au Plated			
Bottom Plunger	Hardened Beryllium copper / Au Plated			
Barrel	Brass / Au Plated			
Spring	Music Wire / Au Plated			
Work Force	45.0gf @ 2.00mm			
Full Travel	64.0gf @ 3.00mm			
Insertion loss (S21) @-1.0dB		34.9 GHz		
Return loss (S11) @-10.0dB		27.1 GHz		
Working Temp.	-40 ~ 120°C			

Problem

Item	Vendor A	Vendor B	Vendor C	Remark
Dimension	OD0.9(0.5) * 13.7(1.8+10.1+1.8)mm			all the same
Top Plunger	Hardened Beryllium copper / Au Plated			all the same
Bottom Plunger	Hardened Beryllium copper / Au Plated			all the same
Barrel	Brass / Au Plated			all the same
Spring	Music Wire / Au Plated			all the same
Work Force	45.0gf @ 2.00mm			all the same
Full Travel	64.0gf @ 3.00mm			all the same
Insertion loss (S21) @-1.0dB	37.4 GHz	34.9 GHz	19.6 GHz	?
Return loss (S11) @-10.0dB	27.8 GHz	27.1 GHz	18.4 GHz	?
Working Temp.	-40 ~ 120°C			all the same

Problem

Item	Vendor A	Vendor B	Vendor C	Remark
Insertion loss (S21)	37.4 GHz	34.9 GHz	19.6 GHz	
Return loss (S11)	26.5 GHz	27.1 GHz	18.4 GHz	

- Based on the data, Vendor A's value is the best.
- The pin length is 13mm. Is this 37.4GHz?
Isn't FEA Simulation trick?
- But, choose Vendor A just by looking at the Numerical.
- Focus on competitively numeric, **reducing trust in data!**

Problem

- Customers require actual data
 - Is it possible to measure with general purpose measuring instruments (VNA, TDR, etc.) under the same conditions as actual use of ATE?
 - Is it possible to measure to obtain the same value as simulation?

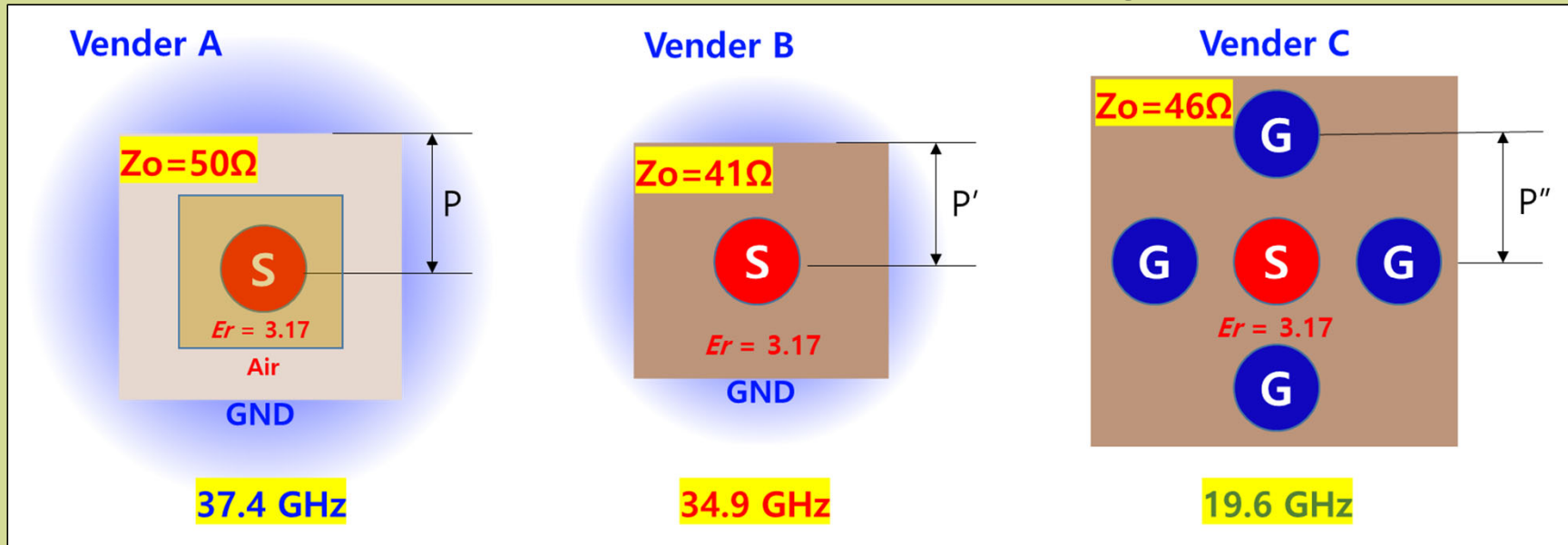
Cause, Optimal conditions

- Low Inductance : Signal length 11.7mm, Fixed
- Low Capacitance : Dielectric value of Housing & Pitch
- Impedance matching : 50Ω

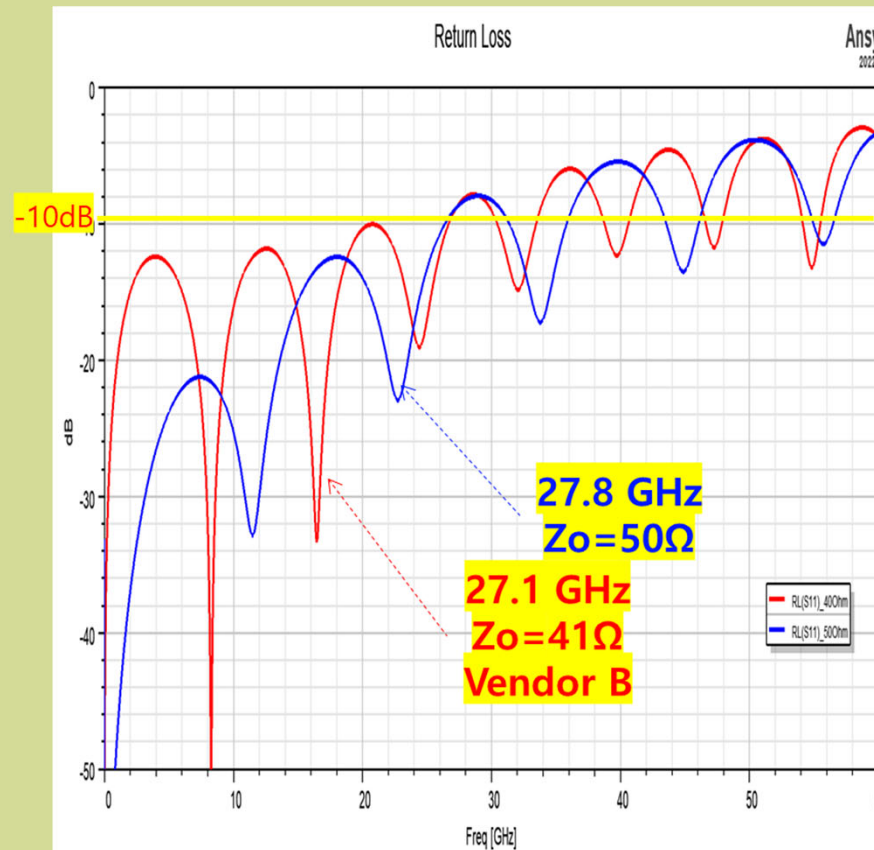
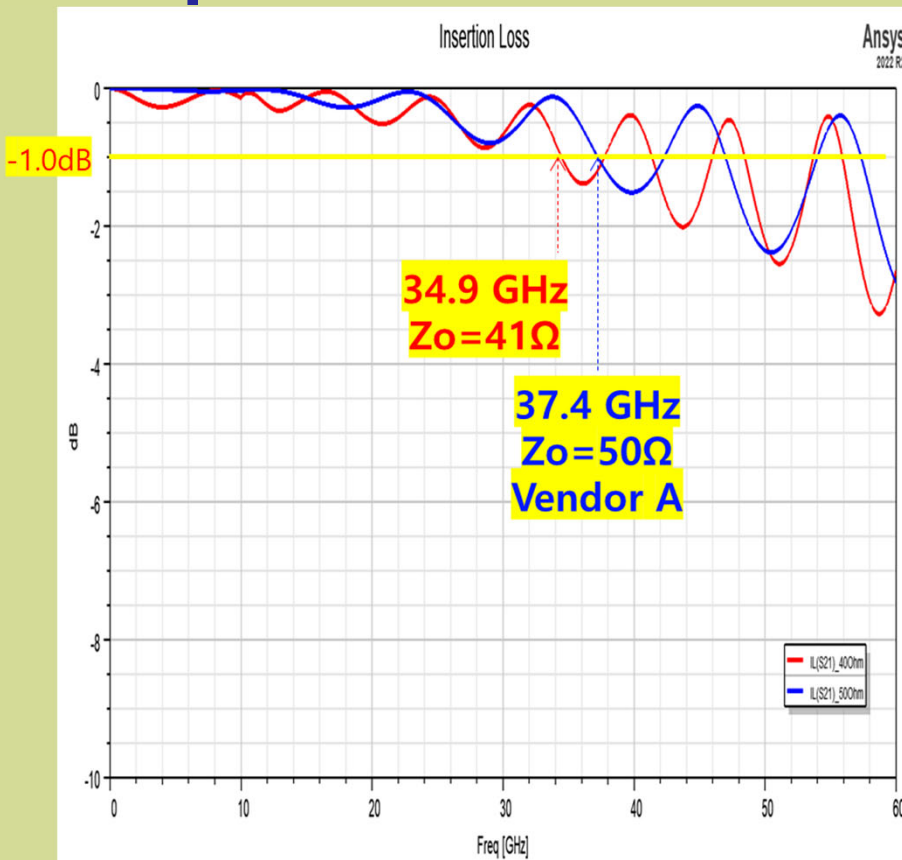
$$Z_o(\Omega) = \frac{138}{\sqrt{Er}} \log \frac{2P}{Pin O.D}$$

Cause, Optimal conditions

: Conditions are different when simulating for each vendor.

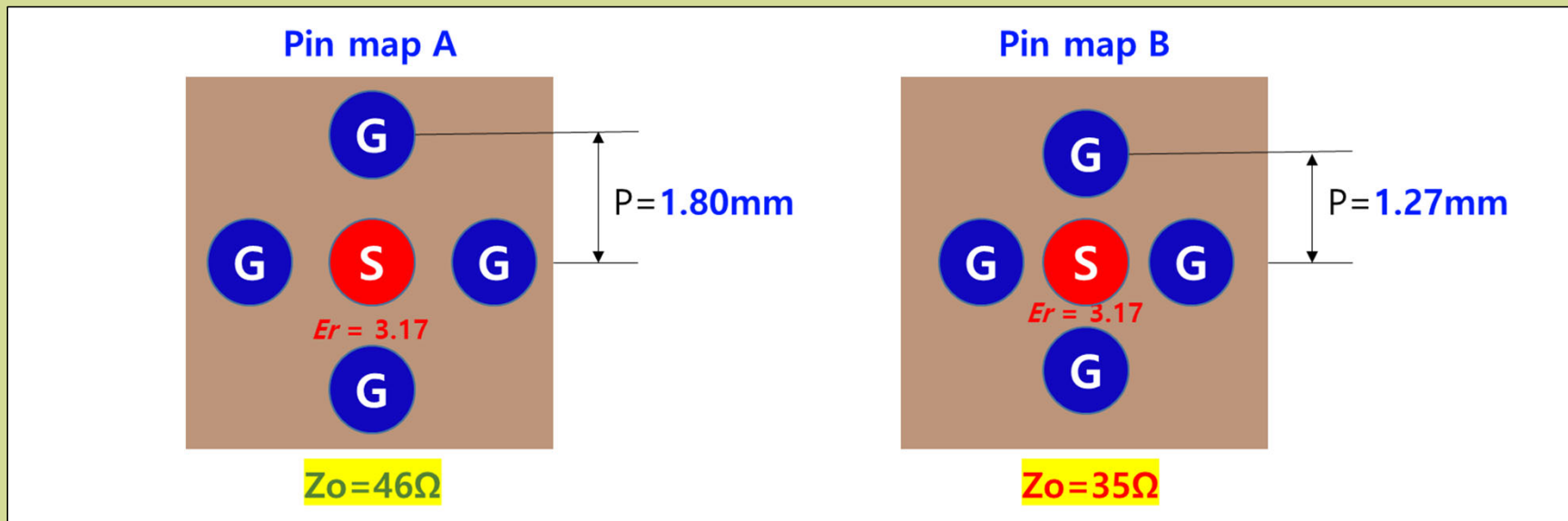


Comparative data between Vendor A and B

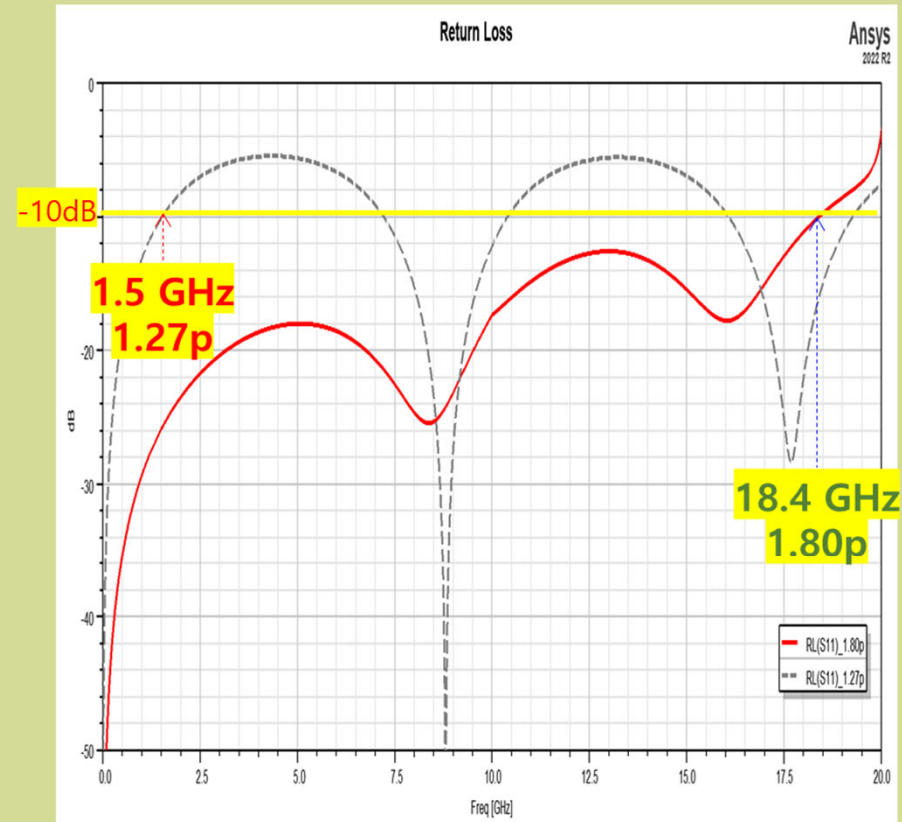
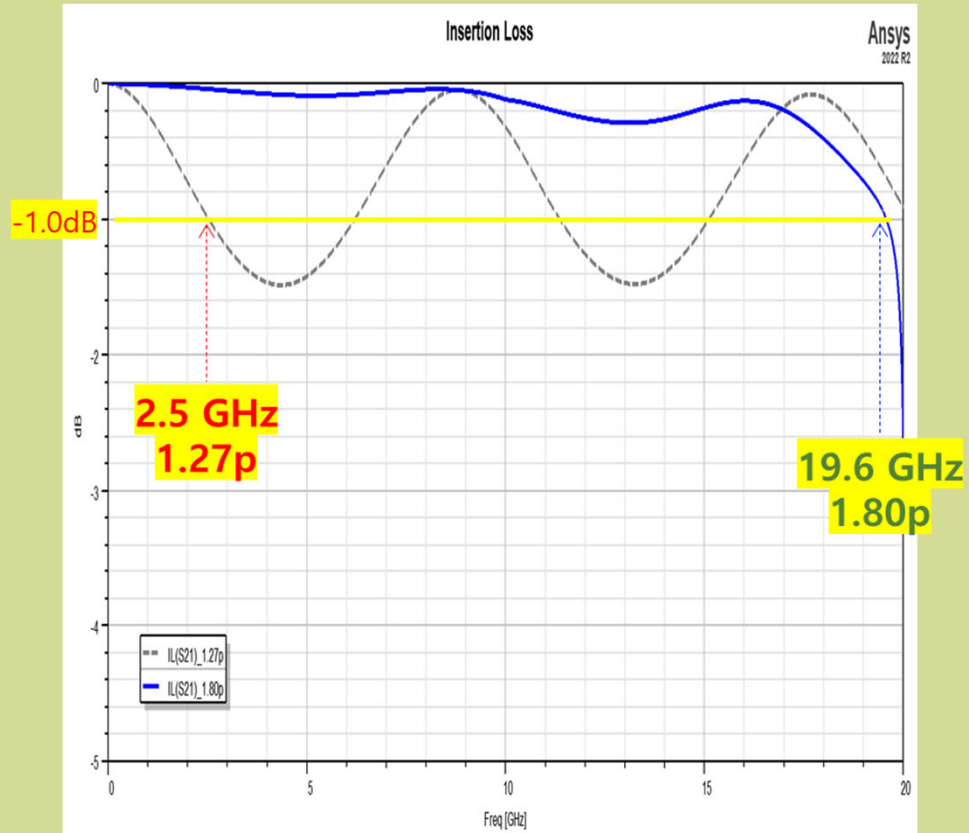


Cause, Optimal conditions

: Try changing the pitch in Vendor C's pin map.

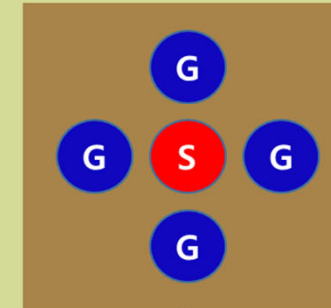
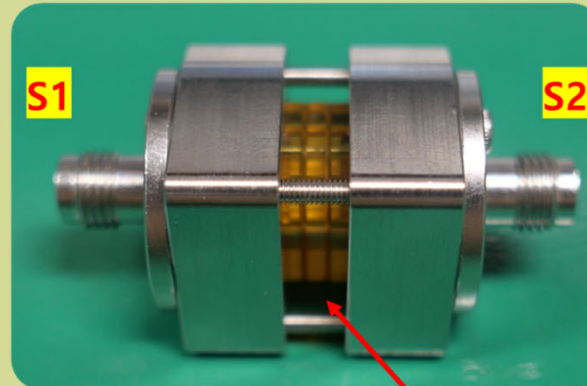
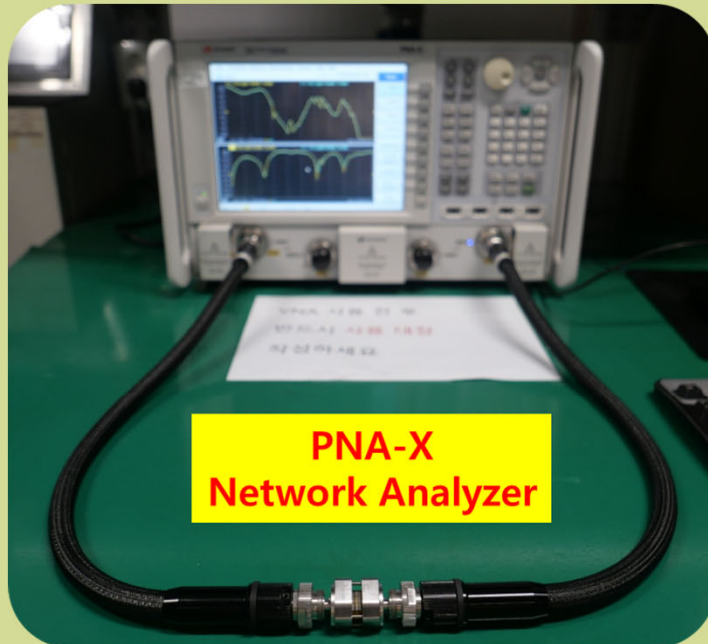


Comparative data between Map A and B



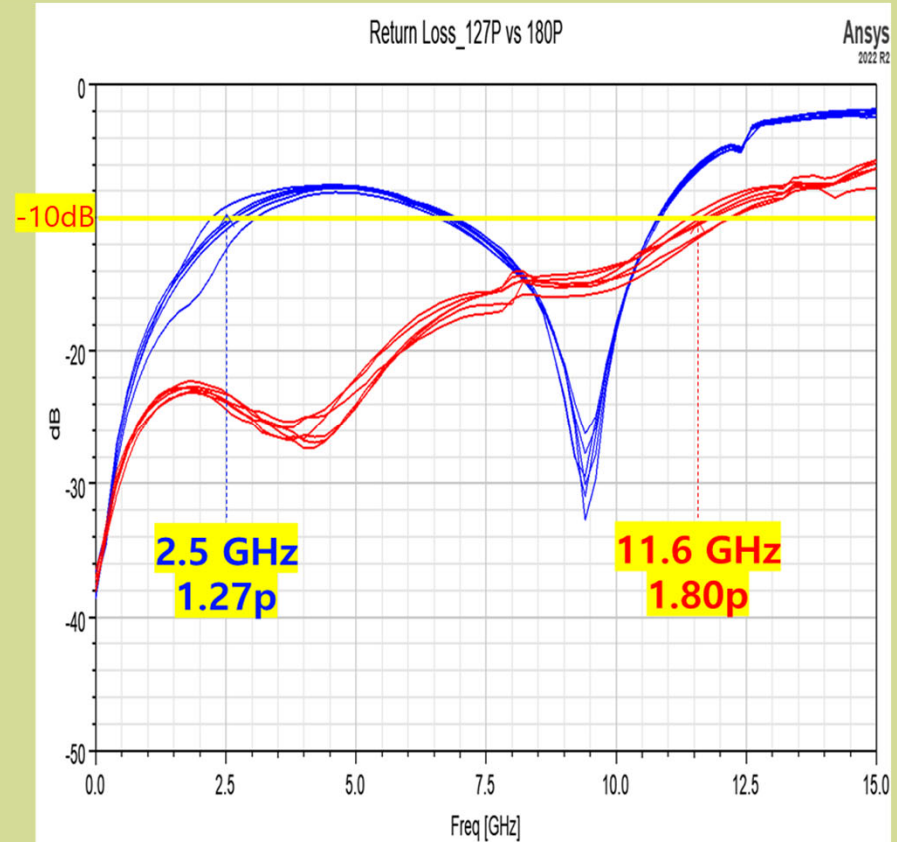
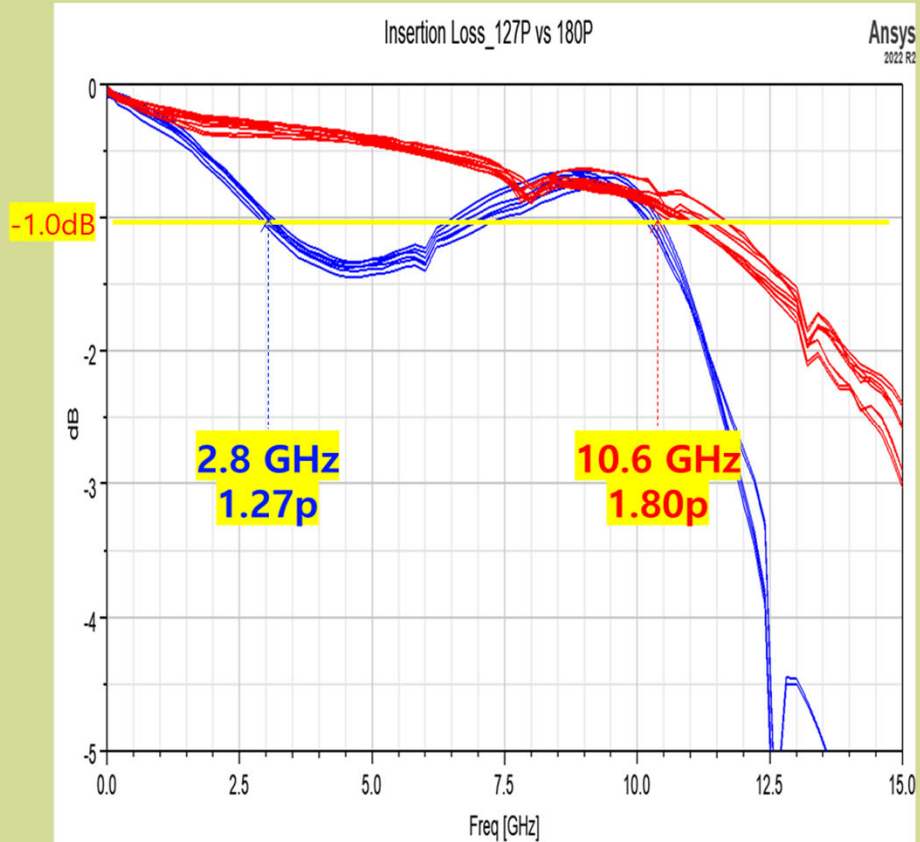
Cause, Optimal conditions

: Now, let's actually measure it!



Pogo Block
(Utem1000)

Measurement data (With In 2.4 Connector)



Data summary

Case	Conditions	Insertion loss (S21) @-1.0dB	Return loss (S11) @-10.0dB	Remark
Vendor A	Force matching to Zo=50Ω	37.4 GHz	27.8 GHz	All same pogo Sample OD0.9*13.7L
Vendor B	Matching to pitch(ISC STD)	34.9 GHz	27.1 GHz	
Pin map A	Surround GND:1.80mm Pitch	19.6 GHz	18.4 GHz	
Pin map B	Surround GND:1.27mm Pitch	2.5 GHz	1.5 GHz	
Measure 1	JIG+2.4Conn:1.80mm Pitch	10.6 GHz	11.6 GHz	
Measure 2	JIG+2.4Conn:1.27mm Pitch	2.8 GHz	2.5 GHz	

Bandwidth is wide and diverse, from 1.5GHz to 37.4 GHz.

Need for standardization

- High-frequency characteristics cannot be determined solely by the contactor's appearance.
- Shorter contactors are good, but housing material matters.
- Match characteristic impedance; it's vital.
- **Therefore:**
 - Contactor-only suppliers, clarify data conditions.
 - Users, mind housing conditions, not just SP Numeric.

Discussion & Conclusion

- 13mm Pogo 37.4GHz, Isn't Simulation trick? : **Not trick**
- Is it possible to measure with VNA measuring instruments under the same conditions as actual use of ATE? : **Challenging...**
- Is it possible to measure to obtain the same value as simulation? : **Possible**
- Recognized international standardization for FEA and measurements is needed.

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